Product Change Notification

(Notification – P2207046-DI)

(PC-SOC-A005A/E)

July 27, 2022

To: *Our Valued Distribution Customer*

The purpose of this notification is to communicate a product change of select Renesas Electronics America, Inc. (REA) devices.

This notification announces the following changes to select RX/T1-M and EC-1 devices. See the appendix for additional details.

- Addition of Advanced Semiconductor Engineering, Inc. as an Assembly Site
- Addition of King Yuan Electronics Co., Ltd. as a Final Test (Sorting) Site
- Additional Package Outline

The new additional device has a new part number, and there is a change to the form. There is no impact to the specifications, fit, characteristics, quality & reliability of the products.

Affected Products: A review of our records indicates the list of products below may affect your company.

Booking Part Number	New Additional Part Number
R7S910020CBG#AC0	R7S910020CBA#BC0
R7S910021CBG#AC0	R7S910021CBA#BC0
R7S910022CBG#AC0	R7S910022CBA#BC0
R7S910023CBG#AC0	R7S910023CBA#BC0
R9A06G043GBG#AC0	R9A06G043GBB#BC0

Part numbers given in this list are for active part numbers in REA database at the time of this notification.

Key Dates:

Shipments from REA of the new additional part numbers begins.	March 31, 2023

Response: No response is required. REA will consider this notification approved 30 days after its issue. If you anticipate volumes beyond your regular rate prior to the transition date, please contact your REA sales representative with a forecast of your requirements.

If the customer provides a timely acknowledgement, the customer shall have 90 days (an additional 60 days) from the date of receipt of this notification in which to make any objections to the notification. If the customer does not make any objections to this notification within 90 days of the receipt of the notification, then Renesas will consider the notification as approved. If customer cannot accept the notification, then the customer must provide Renesas with a last time buy demand and purchase order.

Please contact your REA sales representative for any questions or comments. Thank you for your attention.

Sincerely,

Renesas Electronics America, Inc.

Appendix A: Change Summary

Item	Current	New Additional
Assembly (Location)	Amkor Technology Japan, Inc. (Hakodate, Japan)	Advanced Semiconductor Engineering, Inc. (Kaohsiung, Taiwan)
Final Test (Location)	Amkor Technology Japan, Inc. (Kumamoto, Japan)	King Yuan Electronics Co., Ltd. (Chu-Nan, Taiwan)
Package	No Change	Changed
Tester	No Change	
Test Program	No Change	

Appendix B: Package Outline Change

Current product

RZ/T1-M (112BGA)

	Symbol	Dimension in Millimeters		
		Min.	Nom.	Max.
Package size	D	5.80	6.00	6.20
Package size	E	5.80	6.00	6.20
Total thickness	A	-	-	1.70
Stand off	A1	0.20	0.25	0.30
Ball pitch	e	-	0.50	-
Ball width	b	0.25	0.30	0.35
Ball offset (Package)	x1	-	-	0.20
Ball offset (Ball)	x2	-	-	0.05
Coplanarity	y	-	-	0.08
Mold parallelism	y1	-	-	0.20

Additional product

	Symbol	Dimension in Millimeters		
		Min.	Nom.	Max.
Package size	D	**5.85**	6.00	**6.15**
Package size	E	**5.85**	6.00	**6.15**
Total thickness	A	-	-	**1.35**
Stand off	A1	0.20	0.25	0.30
Ball pitch	e	-	0.50	-
Ball width	b	0.25	0.30	0.35
Ball offset (Package)	x1	-	-	**0.15**
Ball offset (Ball)	x2	-	-	0.05
Coplanarity	y	-	-	0.08
Mold parallelism	y1	-	-	0.20

Current product

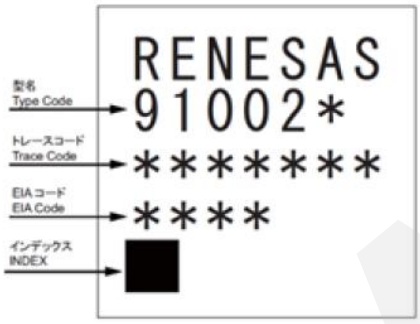
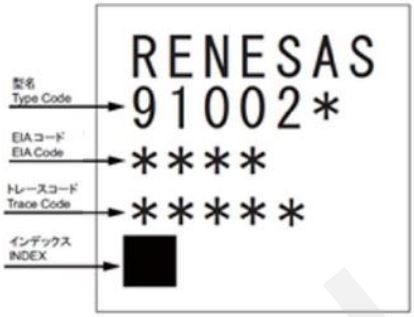
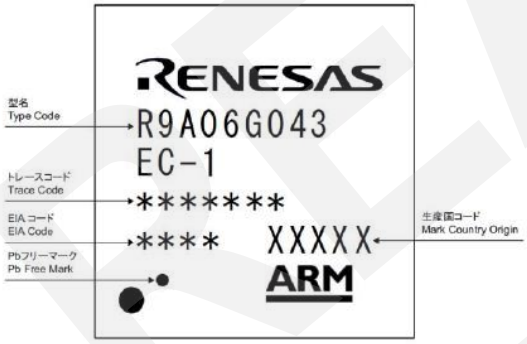
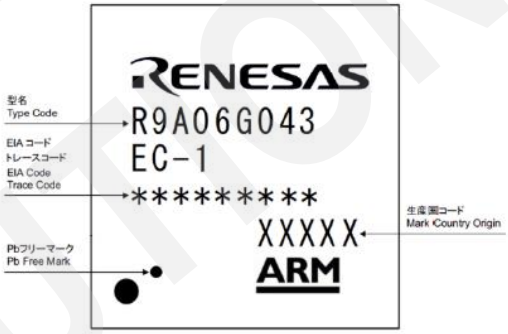
EC-1 (196BGA)

	Symbol	Dimension in Millimeters		
		Min.	Nom.	Max.
Package size	D	11.92	12.00	12.08
Package size	E	11.92	12.00	12.08
Total thickness	A	-	-	1.60
Stand off	A1	0.35	0.40	0.45
Ball pitch	e	-	0.80	-
Ball width	b	0.45	0.50	0.55
Ball offset (Package)	x1	-	-	0.15
Ball offset (Ball)	x2	-	-	0.08
Coplanarity	y	-	-	0.10
Mold parallelism	y1	-	-	0.20

Additional product

	Symbol	Dimension in Millimeters		
		Min.	Nom.	Max.
Package size	D	**11.85**	12.00	**12.15**
Package size	E	**11.85**	12.00	**12.15**
Total thickness	A	-	-	**1.50**
Stand off	A1	**0.36**	**0.41**	**0.46**
Ball pitch	e	-	0.80	-
Ball width	b	0.45	0.50	0.55
Ball offset (Package)	x1	-	-	0.15
Ball offset (Ball)	x2	-	-	0.08
Coplanarity	y	-	-	0.10
Mold parallelism	y1	-	-	0.20

Appendix C: Marking Change

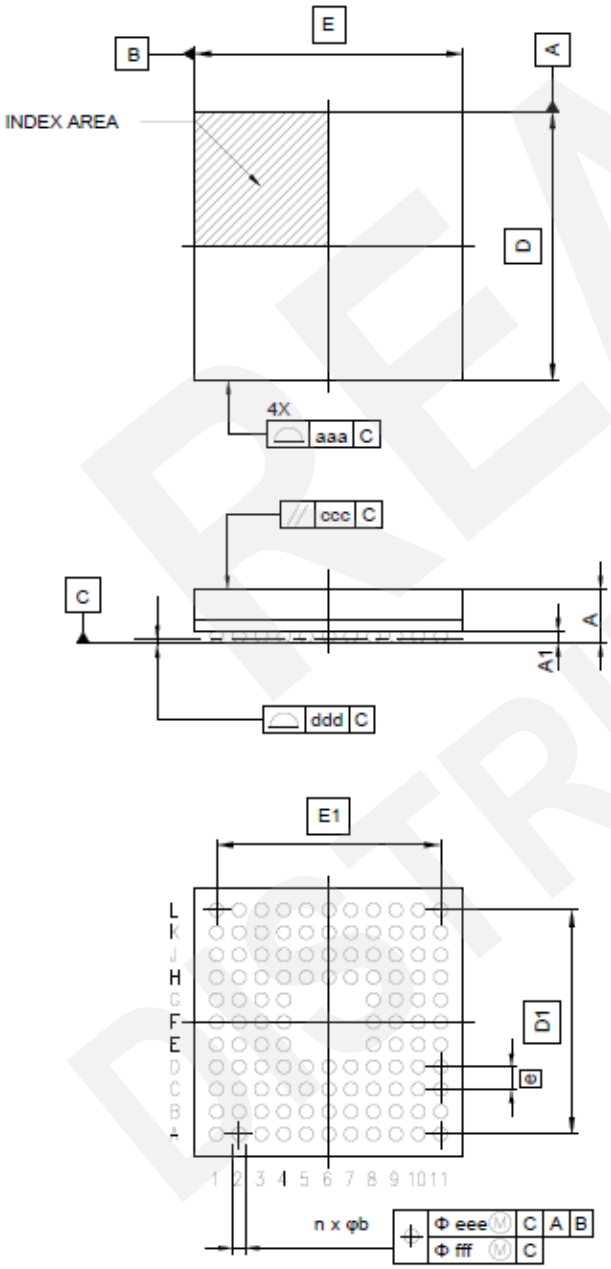
Current product	Additional product
RZ/T1-M (112BGA) 	RZ/T1-M (112BGA) 
EC-1 (196BGA) 	EC-1 (196BGA) 

Appendix D: Packing Label Change

Current product	Additional product
RZ/T1-M (112BGA) D/N: R7S910XXXCBG AC0WL01000 SPN: R7S910XXXCBG#AC0 AC0WL01000 or D/N: R7S910XXXCBG AC0WL02000 SPN: R7S910XXXCBG#AC0 AC0WL02000	D/N: R7S910XXXCBA U03L SPN: R7S910XXXCBA#BC0 BC0M503000
EC-1 (196BGA) D/N: R9A06G043GBG AC0WL01000 SPN: R9A06G043GBG#AC0 AC0WL01000 or D/N: R9A06G043GBG AC0WL02000 SPN: R9A06G043GBG #AC0 AC0WL02000	D/N: R9A06G043GBB U03L SPN: R9A06G043GBB#BC0 BC0M503000

Appendix E: Package Outline Drawing for Additional Product (RZ/T1-M [112BGA])

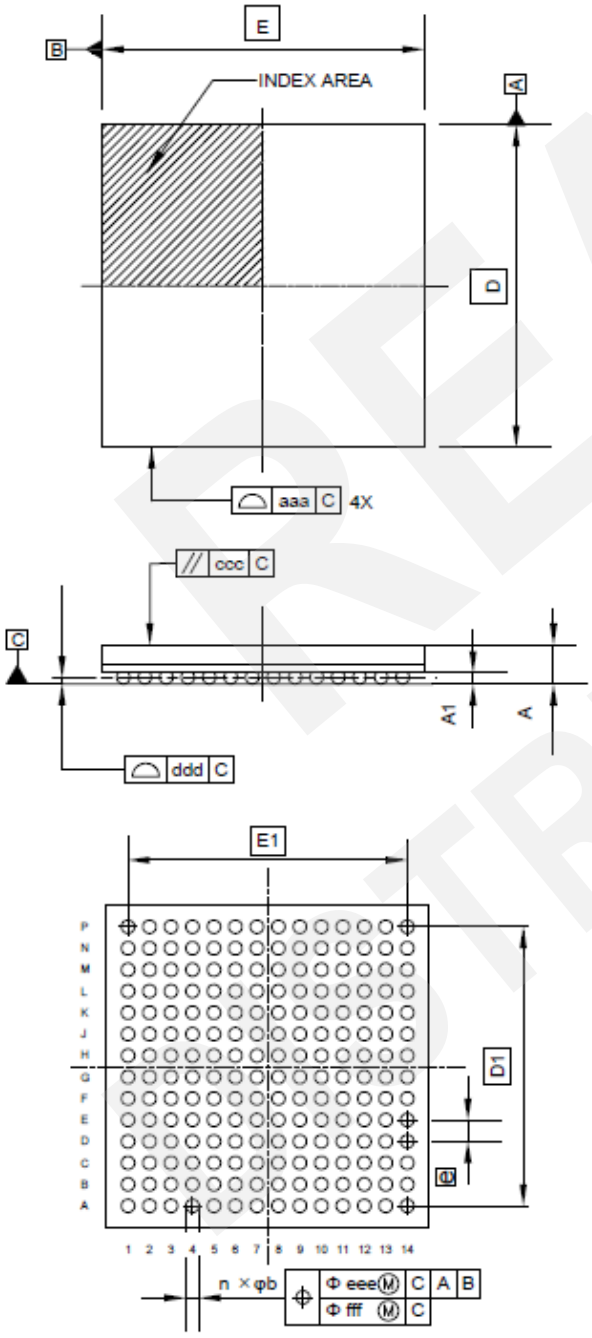
JEITA Package code	RENESAS code	MASS(TYP.)[g]
P-LFBGA112-6x6-0.50	PLBG0112KB-A	0.09



Reference Symbol	Dimension in Millimeters		
	Min.	Nom.	Max.
D	—	6.00	—
E	—	6.00	—
D1	—	5.00	—
E1	—	5.00	—
A	—	—	1.35
A1	0.20	—	—
b	0.25	0.30	0.35
e	—	0.50	—
aaa	—	—	0.15
ccc	—	—	0.20
ddd	—	—	0.08
eee	—	—	0.15
fff	—	—	0.05
n	—	112	—

Appendix F: Package Outline Drawing for Additional Product (EC1 [196BGA])

JEITA Package code	RENESAS code	MASS(TYP.)[g]
P-LFBGA196-12x12-0.80	PLBG0196GB-A	0.43



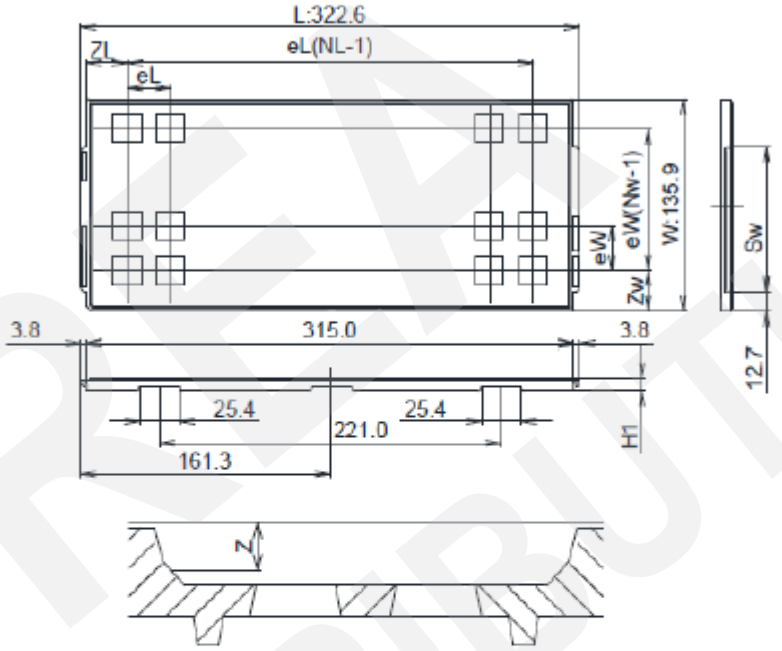
Reference Symbol	Dimension in Millimeters		
	Min.	Nom.	Max.
D	–	12.00	–
E	–	12.00	–
D1	–	10.40	–
E1	–	10.40	–
A	–	–	1.50
A1	0.36	–	–
b	0.45	0.50	0.55
e	–	0.80	–
aaa	–	–	0.10
ccc	–	–	0.20
ddd	–	–	0.10
eee	–	–	0.15
fff	–	–	0.08
n	–	196	–

Appendix G: Packing Specification for Additional Product (RZ/T1-M [112BGA])

包装仕様 Packing Specification
トレイ包装図 TrayOutlineDrawing
BJ-R105

ルネサス エレクトロニクス株式会社
Renesas Electronics Corporation

Unit:mm



The pin1 is located in the hatching portion.

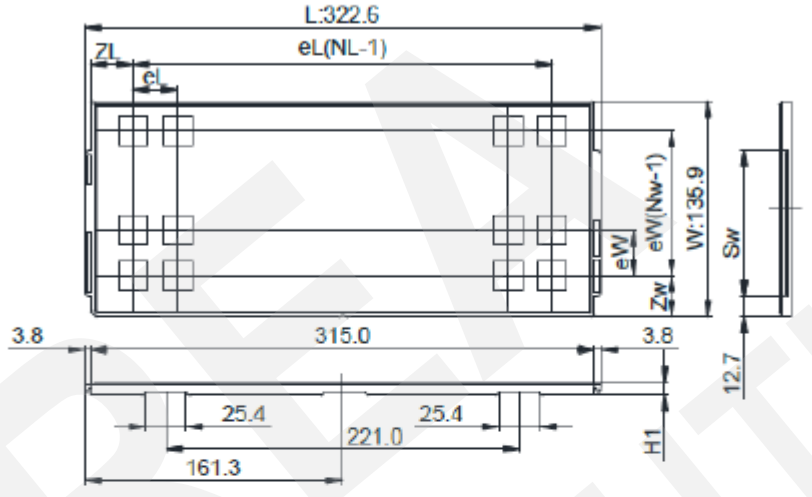
tray Code		BJ-R105
Position dimension of cells	Z	1.65
	Zw	8.15
	ZL	7.90
	eW	9.20
	eL	8.80
	Sw	92.10
Thickness (mm)	H1	7.62
Number of cells	Nw	14
	NL	35
Maximum storage Pcs. IC/Tray		490
Maximum storage Pcs. IC/Inner box		3920
Material		Carbon PPE
Heat resistant temperature		135℃MAX
JEDECorCustom		JEDEC
Surface resistance		1.0x10^4≦R<1.0x10^11Ω

Appendix H: Packing Specification for Additional Product (EC1 [196BGA])

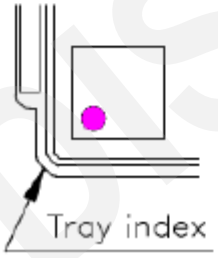
包装仕様 Packing Specification
トレイ包装図 TrayOutlineDrawing
EA7121224-10 REV.A

ルネサス エレクトロニクス株式会社
Renesas Electronics Corporation

Unit:mm



The pin1 is located in the hatching portion.



Tray Code		EA7121224-10 REV.A
Position dimension of cells	Z	2.01
	Zw	11.95
	ZL	11.00
	eW	16.00
	eL	14.65
	Sw	92.1
Thickness (mm)	H1	7.62
Number of cells	Nw	8
	NL	21
Maximum storage Pcs. IC/Tray		168
Maximum storage Pcs. IC/Inner box		1344
Material		Carbon PPE
Heat resistant temperature		135°CMAX
JEDECorCustom		JEDEC
Surface resistance		1.0x10^4≦R<1.0x10^11Ω